

R0E53032ACSJC0

Converter Board for Connecting R8C/32A Group 20-pin 0.65mm pitch LSSOP

User's Manual

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CAUTION

If the requirements shown in the "CAUTION" sentences are ignored, the equipment may cause personal injury or damage to the products.

1. Outline

The R0E53032ACSJC0 is a converter board for connecting the signals of the MCU unit R0E521300MCU00 for R8C/Tiny Series to a foot pattern for 20-pin 0.65mm pitch LSSOP of R8C/32A group.

2. Package Components (See Figure 1)

Check to see if the R0E53032ACSJC0 package has all the following contents before using this product.

- (1) R0E53032ACSJC0 converter board..... 1 pc.
- (2) YSPACK20BG (made by Tokyo Eletech Corporation)..... 1 pc.
- (3) NSPACK20BG (made by Tokyo Eletech Corporation) 1 pc.
- (4) YS-GUIDE (made by Tokyo Eletech Corporation) 2 pcs.
- (5) R0E53032ACSJC0 User's Manual (this manual)

3. Specifications

Table 1 Specifications

Applicable package	PLSP0020JB-A: formerly 20P2F-A (20-pin 0.65mm pitch LSSOP)
Insertion/removal iterations of connector	50 times guaranteed

4. Usage (See Figure 2)

The R0E53032ACSJC0 can be used for debugging and on-board evaluation in common by mounting the NSPACK20BG on the user system.

- (1) For debugging
Mount the NSPACK20BG on the foot pattern of the user system and attach the YSPACK20BG on it. In addition, connect the R0E53032ACSJC0 to the YSPACK20BG, and then connect the flexible cable R0E001000FLX10 of the emulator to the upper connector of the R0E53032ACSJC0.
- (2) For on-board evaluation
Mount an MCU with on-chip flash memory or one-time PROM and the HSPACK20BG (not included) in order on the NSPACK20BG on the user system.

Before using the R0E53032ACSJC0, be sure to read "7. Precautions" on page 4.

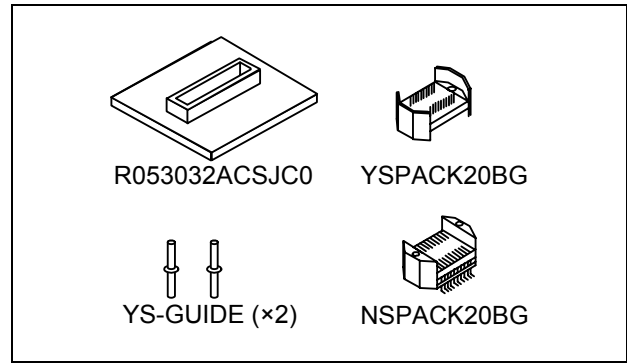


Figure 1 Package components of the R0E53032ACSJC0

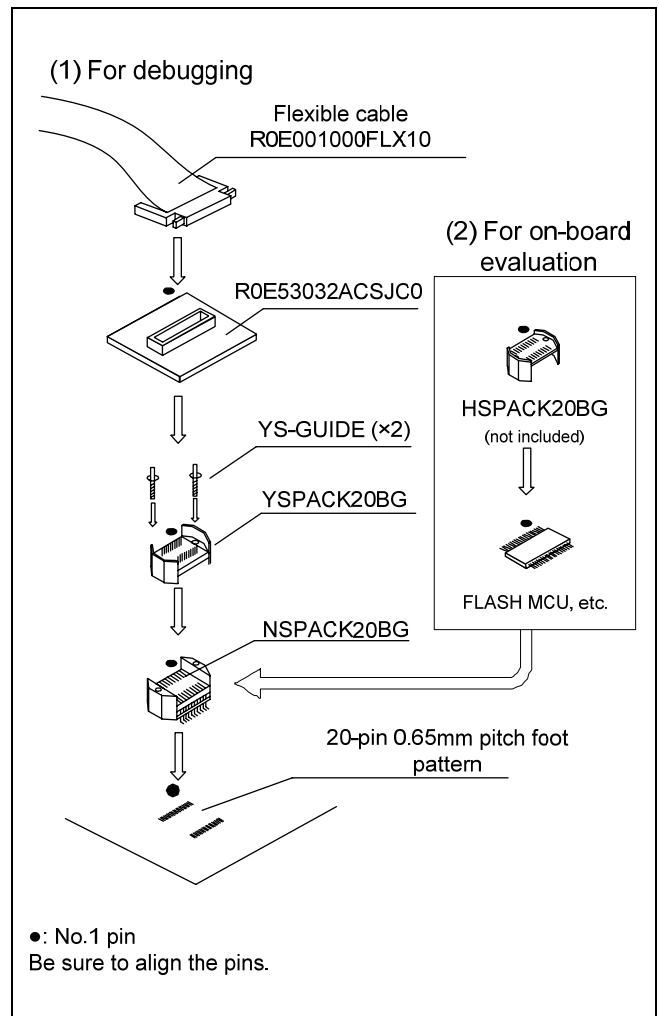


Figure 2 Usage of the R0E53032ACSJC0

5. Connection Procedure (See Figure 3)

The procedure for connecting the R0E53032ACSJC0 is shown below.

- (1) Mount the NSPACK20BG on the user system.
- (2) Attach the YSPACK20BG on the NSPACK20BG.
- (3) Secure the two sides of the YSPACK20BG with the YS-GUIDEs.

- Do not use the screws included with the YSPACK20BG for fixing the YSPACK20BG.
- Do NOT use the screwdriver included with the NSPACK20BG for fixing the YS-GUIDEs. That is used only for the HSPACK20BG.

- (4) Mount the R0E53032ACSJC0 on the YSPACK20BG.
- (5) Connect the flexible cable R0E001000FLX10 of the emulator to the R0E53032ACSJC0.

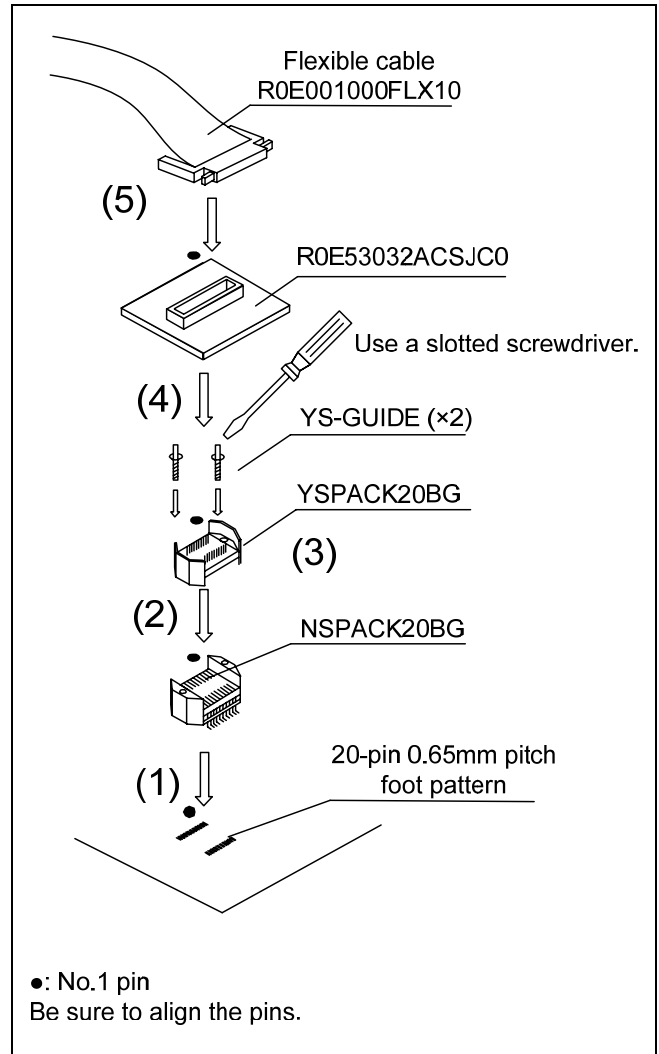


Figure 3 Connection procedure of the R0E53032ACSJC0

6. External Dimensions and a Sample Foot Pattern

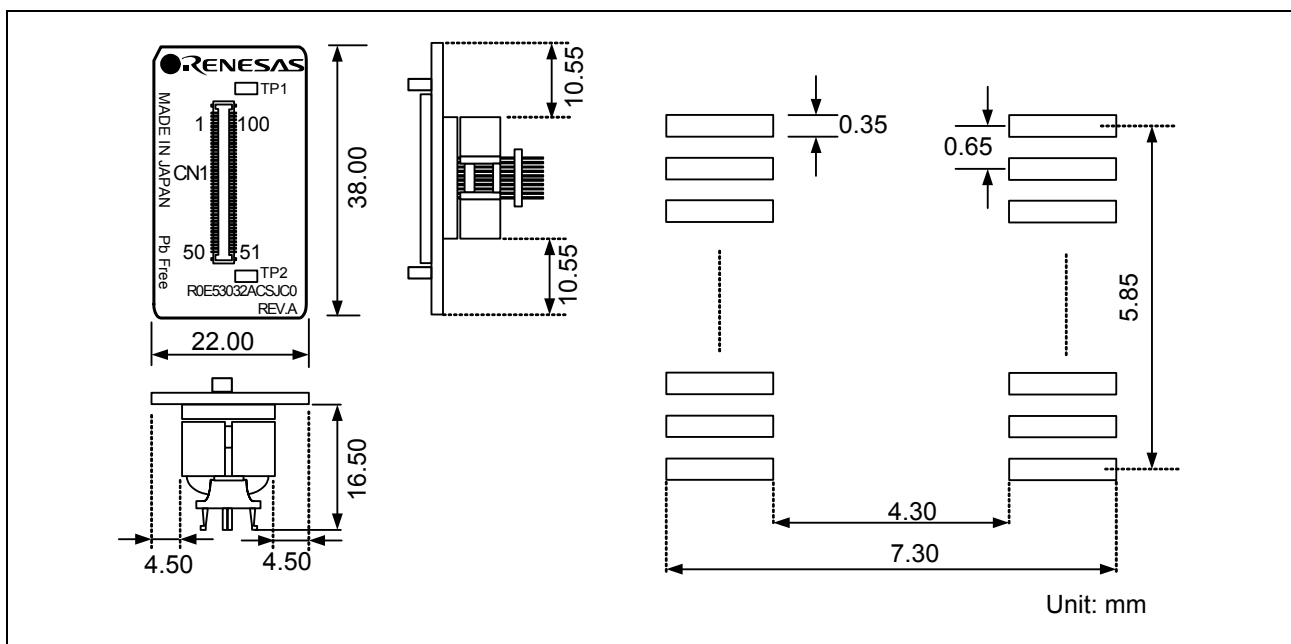


Figure 4 External dimensions and a sample foot pattern of the R0E53032ACSJC0

7. Precautions

⚠ CAUTION

Cautions to Be Taken for This Product:



- When connecting the YSPACK20BG, be sure to use the included YS-GUIDEs.
- Do NOT use the screws included with the YSPACK20BG for connecting the YSPACK20BG.

IMPORTANT

Notes on This Product:

- We cannot accept any request for repair.
- For purchasing the NSPACK20BG, YSPACK20BG, HSPACK20BG, contact the following:
Tokyo Eletech Corporation http://www.tetc.co.jp/e_index.htm
- For inquiries about the product or the contents of this manual, contact your local distributor.
Renesas Tools Homepage <http://www.renesas.com/tools>

8. Correspondence of Connectors CN1

Table 2 Correspondence of the connectors

CN1 Pin No.	IC1	CN1 Pin No.	IC1
1	-	100	-
2	-	99	-
3	-	98	-
4	-	97	-
5	15	96	14
6	16	95	13
7	17	94	12
8	18	93	-
9	19	92	-
10	20	91	-
11	-	90	-
12	-	89	-
13	-	88	-
14	-	87	-
15	-	86	-
16	-	85	-
17	-	84	-
18	-	83	-
19	-	82	-
20	-	81	-
21	-	80	-
22	-	79	-
23	-	78	-
24	-	77	-
25	-	76	-
26	-	75	-
27	-	74	-
28	-	73	-
29	-	72	-
30	-	71	-
31	-	70	-
32	-	69	-
33	-	68	-
34	-	67	-
35	-	66	11
36	-	65	10
37	-	64	-
38	-	63	9
39	-	62	8
40	-	61	-
41	-	60	-
42	1	59	-
43	2	58	-
44	-	57	-
45	3	56	7
46	4	55	6
47	-	54	5
48	-	53	-
49	-	52	-
50	-	51	-

(-: No connection or signals in the emulator)